

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently amended) A computer assembly comprising:

a chassis;

a mounting module rigidly coupled to the chassis, the mounting module for cooling the computer assembly; and

~~at least one~~ a circuit board suspended from the module, wherein the mounting module is coupled to a processor on the circuit board, and wherein the circuit board is connected to the module at an adjusted equilibrium spatial orientation of the circuit board that accommodates the coupling of the module and the processor, wherein the connection is provided by at least one spring connector and at least one rigid connector, wherein the at least one spring connector allows the adjusting of spatial orientation of the circuit board relative to the module for connection to enable the equilibrium spatial orientation, and wherein the at least one rigid connector adapts to the equilibrium spatial orientation and stabilizes and maintains the equilibrium orientation of the circuit board relative to the module ~~the at least one circuit board having a known orientation relative to the module and at least one circuit board having a variable orientation relative to the chassis.~~

2. (Cancelled)

3. (Currently amended) The computer assembly of claim 1 wherein the mounting module comprises[:] a heatsink; ~~and a daughter board coupled to the heatsink, wherein the daughter board includes a processor.~~

4. (Currently amended) The computer assembly of claim 3 wherein a thermal interface material is provided between the processor and the heatsink ~~is in contact with the at least one circuit board.~~

5. (Currently amended) The computer assembly of claim [3] 1 wherein the ~~daughter board is coupled to the heatsink via~~ spring connector includes a spring-loaded mount.

6. (Cancelled)

7. (Currently amended) The computer assembly of claim [6] 1 wherein the ~~fasteners of the printed circuit~~ rigid connectors include a portion that is positioned to expand longitudinally parallel to the surface of the circuit board within an aperture ~~apertures in the daughter circuit board to secure the circuit board to the heatsink assembly module without altering the equilibrium spatial orientation of the circuit board.~~

8. (Currently amended) The computer assembly of claim [7] 3 wherein the circuit board is a main logic board of the computer assembly, and wherein heatsink ~~assembly~~ is located relative to the ~~at least one printed circuit~~ main logic board via pin features, wherein

the pin features include at least one fine locator pin and at least one coarse locator pin.

9. (Currently amended) A mounting module for a computer assembly comprising:
a heatsink assembly for cooling the computer assembly, wherein the heatsink assembly is coupled rigidly to a chassis of the computer assembly and is also coupled to a processor on a printed circuit board within the computer assembly; wherein the printed circuit board has a known orientation relative to the module and has a variable orientation relative to the chassis

at least one spring connector coupled between the heatsink assembly and the circuit board, the at least one spring connector allowing the circuit board to be connected to the heatsink assembly at an adjusted equilibrium spatial orientation of the circuit board that accommodates the coupling of the heatsink assembly and the processor; and

at least one rigid connector coupled between the heatsink assembly and the circuit board, the at least one rigid connector adapting to the equilibrium spatial orientation and stabilizing and maintaining the equilibrium orientation of the circuit board relative to the module.

10. (Cancelled)

11. (Currently amended) The mounting module of claim 9 wherein the heatsink assembly comprises[:]
a heatsink, and wherein the equilibrium position of the circuit board allows a tight coupling between the heatsink and the processor to insure adequate power

dissipation from the processor; and a daughter board coupled to the heatsink, wherein the daughter board includes a processor.

12. (Currently amended) The mounting module of claim 11 wherein a thermal interface material is provided between the processor and the heatsink assembly ~~is in contact with the at least one circuit board.~~

13. (Currently amended) The mounting module of claim [11] 2 wherein the ~~daughter board is coupled to the heatsink via~~ spring connector includes a spring-loaded mount.

14. (New) The computer assembly of claim 7 wherein the portion of the at least one rigid connector is a standoff, and wherein the rigid connector includes a fastener to be inserted within the standoff through an aperture in the circuit board, wherein a clearance space is provided between the standoff and the aperture that allows the standoff to adjust and expand parallel to the surface of the circuit board within the aperture when the fastener is inserted.

15. (New) The computer assembly of claim 7 wherein the circuit board is a daughter board which is connected with a main logic board of the computer assembly.

16. (New) The computer assembly of claim 7 wherein the circuit board is a main logic board of the computer assembly.

17. (New) The mounting module of claim 9 wherein the rigid connectors include a portion that is positioned to expand parallel to the surface of the circuit board within an aperture in the circuit board to secure the circuit board to the module without altering the equilibrium spatial orientation of the circuit board.

18. (New) The mounting module of claim 17 the portion of the at least one rigid connector is a standoff, and wherein the rigid connector includes a fastener to be inserted within the standoff through an aperture in the circuit board, wherein a clearance space is provided between the standoff and the aperture that allows the standoff to adjust and expand parallel to the surface of the circuit board within the aperture when the fastener is inserted.

19. (New) The computer assembly of claim 9 wherein the circuit board is a daughter board which is connected with a main logic board of the computer assembly.

20. (New) The computer assembly of claim 9 wherein the circuit board is a main logic board of the computer assembly.

21. (New) The computer assembly of claim 9 wherein the at least one spring connector is separate from the at least one rigid connector.

22. (New) A method for securing a mounting module in a computer assembly

comprising:

attaching a circuit board to a heatsink assembly for cooling the computer assembly, such that the heatsink assembly is coupled rigidly to a chassis of the computer assembly and is coupled to a processor on the circuit board within the computer assembly, wherein the circuit board is attached to the heatsink assembly by adjusting the spatial orientation of the circuit board to an equilibrium position that accommodates the coupling of the heatsink assembly and the processor, wherein the adjustment of the spatial orientation of the circuit board is allowed by at least one spring connector coupled between the heatsink assembly and the circuit board; and

stabilizing and maintaining the equilibrium position of the circuit board by coupling at least one rigid connector between the heatsink assembly and the circuit board, the rigid connector adapting to the equilibrium position allowed by the at least one spring connector.

23. (New) The method of claim 22 wherein the at least one rigid connector includes a standoff positioned to expand parallel to the surface of the circuit board within an aperture in the circuit board when a fastener is inserted in the standoff to secure the circuit board to the heatsink assembly by self-adjusting without altering the equilibrium spatial orientation of the circuit board.

24. (New) The method of claim 22 wherein the circuit board is a daughter board, and wherein the daughter board and the heatsink assembly comprise the mounting module, and further comprising performing blind engagement of the mounting module with a main logic

board of the computer assembly, the blind engagement assisted by tapered pin features, the pin features including at least one fine locator pin and at least one coarse locator pin.